


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

| | | |
|-----------------------------|--|--------------------------------------|
| 1.1 Company |  | STMicroelectronics International N.V |
| 1.2 PCN No. | MDG/24/14374 | |
| 1.3 Title of PCN | AMKOR ATP (Philippines) UFBGA package copper palladium bonding wire introduction on STM32F2x/4x/7x, STM32G0x/4x and STM32L0x/1x/4x/5x listed products. | |
| 1.4 Product Category | STM32F2x, STM32F4x, STM32F7x, STM32G0x, STM32G4x, STM32L0x, STM32L1x, STM32L4x, STM32L5x | |
| 1.5 Issue date | 2024-09-24 | |

2. PCN Team

| | |
|----------------------------------|----------------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | PIKE EMMA |
| 2.1.2 Phone | +44 1628896111 |
| 2.1.3 Email | emma.pike@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Ricardo Antonio DE SA EARP |
| 2.1.2 Marketing Manager | Veronique BARLATIER |
| 2.1.3 Quality Manager | Pascal NARCHE |

3. Change

| | | |
|---------------------|---|-----------------------------------|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| Materials | New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter | AMKOR ATP (Philippines) |

4. Description of change

| | | |
|---|---|---|
| | Old | New |
| 4.1 Description | Current Wire bonding material: - AMKOR ATP (Philippines) gold wire - ASE Kaohsiung (Taiwan) gold and Copper Palladium wire. | Current Wire bonding material: - AMKOR ATP (Philippines) gold wire - ASE Kaohsiung (Taiwan) gold and Copper Palladium wire. New Wire bonding material : - AMKOR ATP (Philippines) copper palladium wire |
| 4.2 Anticipated Impact on form, fit, function, quality, reliability or processability? | no impact on form, Fit, Function | |

5. Reason / motivation for change

| | |
|-----------------------------|---------------------|
| 5.1 Motivation | To improve service |
| 5.2 Customer Benefit | SERVICE IMPROVEMENT |

6. Marking of parts / traceability of change

| | |
|------------------------|---|
| 6.1 Description | traceability ensured by ST Internal tools |
|------------------------|---|

7. Timing / schedule

| | |
|--|--------------|
| 7.1 Date of qualification results | 2024-10-16 |
| 7.2 Intended start of delivery | 2024-12-16 |
| 7.3 Qualification sample available? | Upon Request |

8. Qualification / Validation

| | | | |
|---|--|-------------------|------------|
| 8.1 Description | 14374 MDRF-GPM-RER2331 PCN14374 ATP3 UFBGA CuPd wire - products reliability plan.pdf | | |
| 8.2 Qualification report and qualification results | Available (see attachment) | Issue Date | 2024-09-24 |

9. Attachments (additional documentations)

14374 Public product.pdf
14374 MDRF-GPM-RER2331 PCN14374 ATP3 UFBGA CuPd wire - products reliability plan.pdf
14374 PCN14374_Additional information.pdf

10. Affected parts

| 10.1 Current | | 10.2 New (if applicable) |
|-------------------------|-------------------------|--------------------------|
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| | STM32F207IGH6 | |
| | STM32F217IGH6 | |
| | STM32F407IGH6 | |
| | STM32F411VEH6 | |
| | STM32F413ZGJ6 | |
| | STM32F417IGH6 | |
| | STM32F427AIH6 | |
| | STM32F429AGH6 | |
| | STM32F429AIH6 | |
| | STM32F429IEH6 | |
| | STM32F437IIH6 | |
| | STM32F439IIH6U | |
| | STM32F446ZEH6 | |
| | STM32F446ZEJ6 | |
| | STM32F756IGK6 | |
| | STM32H750IBK6 | |
| | STM32L151QEH6 | |
| | STM32L152QEH6 | |
| | STM32L4R9ZGJ6 | |
| | STM32L4S9AII6 | |

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